<table>
<thead>
<tr>
<th>ALL NETS ARE VEDIED FROM TOP SIDE</th>
<th>BOM No.</th>
<th>TCKN-OL801</th>
<th>PCB EL</th>
<th>SIR PCB Not In Verason(Central)</th>
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<tbody>
<tr>
<td>LAYER NAME = PCB Board Dimensions</td>
<td>TID No.</td>
<td>N-R</td>
<td></td>
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<tr>
<td>FLOOR NAME = Board Dimensions</td>
<td>GENERATED</td>
<td>2/9-2017</td>
<td>12.23X15 PR</td>
<td>TEXAS INSTRUMENTS</td>
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